

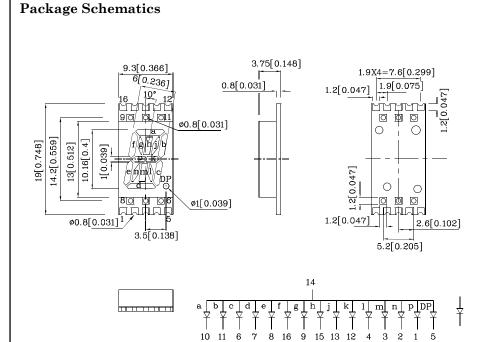
## Part Number: XZFABBA10A

### SURFACE MOUNT DISPLAY

#### Features

- $\bullet$  0.4 inch digit height
- $\bullet$  Robust package
- Low power consumption
- Standard configuration: Gray face w/ white segments
- Standard Package: 400pcs/ Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS compliant







ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



1. All dimensions are in millimeters (inches), Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted. 2. Specifications are subject to change without notice.

3. The gap between the reflector and PCB shall not exceed 0.25mm.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)	Blue (InGaN)	Unit		
Reverse Voltage	$V_{\mathrm{R}}$	5	V	
Forward Current	$I_{\rm F}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	100	mA	
Power Dissipation	$\mathbf{P}_{\mathrm{D}}$	120	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	-40 ~ +85 °C	
Storage Temperature	Tstg	$-40 \sim +85$	•C	
Electrostatic Discharge Thresho (HBM)	1000	V		

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Part

Number

Operating Characteristics (T <sub>A</sub> =25°C)		Blue (InGaN)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	$V_{\mathrm{F}}$	3.05	V
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	$V_{\mathrm{F}}$	3.4	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	$I_{R}$	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I <sub>F</sub> =10mA)	λΡ	468*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I <sub>F</sub> =10mA)	λD	465*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =10mA)	$ riangle\lambda$	21	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	100	$_{ m pF}$
Luminous Intensity Wavelength CIE127-2007* CIE127-2007* (I <sub>F</sub> =10mA) nm ucd λP		Description	
min trin			

			uc	:d	$\lambda P$	
			min.	typ.		
XZFABBA10A	Blue	InGaN	2200*	5790*	468*	Common Anode, Rt.Hand Decimal.
AT	1 .1 .	1		1 1		

L

Emitting

Material

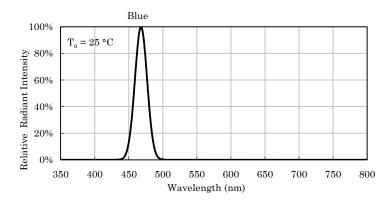
\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Mar 26.2019

Emitting

Color

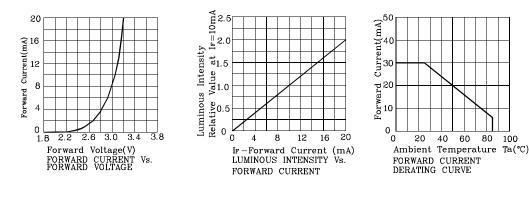
XDSB1636 V8-Z Layout: Maggie L.

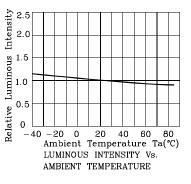




Relative Intensity Vs. CIE Wavelength

Blue





### LED is recommended for reflow soldering and soldering profile is shown below.

300 above 255°C (°C) 260°C max. 30s max. 10s max. 250 3°C/s max. 6°C/s max. 200 150 Temperature pre-heating 100 150~200°C above 217°C 60~120s 60~150s 50 -25℃ 0 0 50 100 150 200 250 300 (sec) Time Notes:

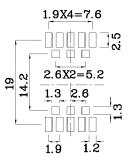
Reflow Soldering Profile for SMD Products (Pb-Free Components)

1. All temperatures refer to the center of the package,

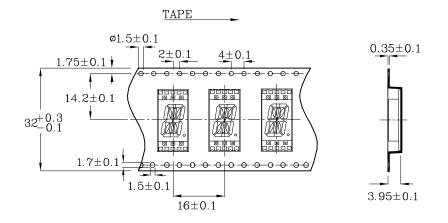
measured on the package body surface facing up during reflow. 2. Do not apply any stress to the LED during high temperature conditions. 3. Maximum number of soldering passes: 2



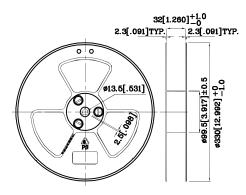
# **&** Recommended Soldering Pattern (Units : mm; Tolerance: ±0.15)



# Tape Specification (Units : mm)



### Reel Dimension



#### Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

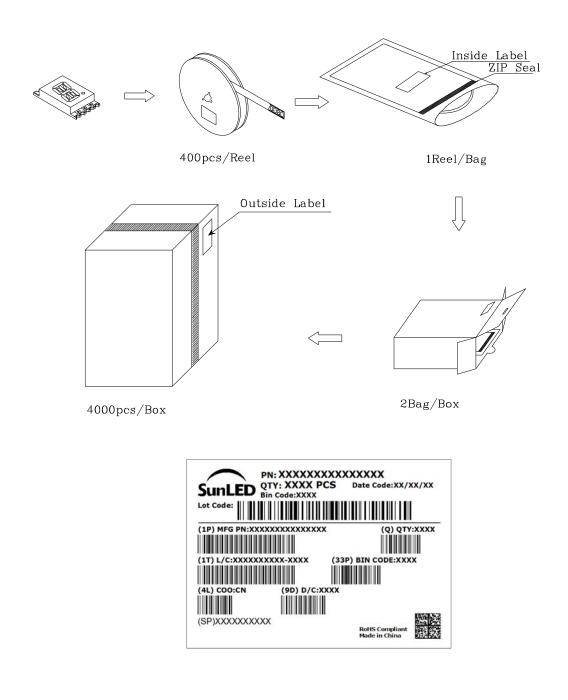
2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



## PACKING & LABEL SPECIFICATIONS



#### TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- 6.When any special process such as potting is required for LED assembly, please consult with SunLED representative before proceeding.
- 7. Additional technical notes are available at <u>https://www.SunLEDusa.com/TechnicalNotes.asp</u>